

	Type	Hits	Search Text	DBs	Time Stamp
1	BRS	0	multi\$3 near layer with inside with (semiconductor or chip or die or IC or active near components) and (substrate or core) with (inorganic and thermosetting near resin) and (via or opening or open)	USPAT	2002/12/ 01 17:45
2	BRS	1	multi\$3 near layer with inside with (semiconductor or chip or die or IC or active near components) and (inorganic and thermosetting near resin) and (via or opening or open)	USPAT	2002/11/ 29 21:38
3	BRS	1	"5780776".PN.	USPAT	2002/11/ 29 21:33
4	BRS	1	"5814883".PN.	USPAT	2002/11/ 29 21:34
5	BRS	1	"5901050".PN.	USPAT	2002/11/ 29 21:34
6	BRS	1	"5901050".PN.	USPAT	2002/11/ 29 21:36
7	BRS	1	"6015722".PN.	USPAT	2002/11/ 29 21:36
8	BRS	1	"6025648".PN.	USPAT	2002/11/ 29 21:37
9	BRS	1	"6183592".PN.	USPAT	2002/11/ 29 21:37
10	BRS	1	"6222265".PN.	USPAT	2002/11/ 29 21:37
11	BRS	1	"6248959".PN.	USPAT	2002/11/ 29 21:37
12	BRS	1	"6265772".PN.	USPAT	2002/11/ 29 21:37
13	BRS	1	"5814883".PN.	USPAT	2002/11/ 29 21:37
14	BRS	1	"5780776".PN.	USPAT	2002/11/ 29 21:37
15	BRS	1	"6025648".PN.	USPAT	2002/11/ 29 21:38
16	BRS	1	"6015722".PN.	USPAT	2002/11/ 29 21:38

	Type	Hits	Search Text	DBs	Time Stamp
17	BRS	1	"5780776" and multi\$3 near layer and (semiconductor or chip or die or IC or active near components) and (inorganic near filler and thermosetting near resin) and (via or opening or open)	USPAT	2002/11/29 21:39
18	BRS	1	"6015722" and multi\$3 near layer and (semiconductor or chip or die or IC or active near components) and (inorganic near filler and thermosetting near resin) and (via or opening or open)	USPAT	2002/11/29 21:39
19	BRS	54	multi\$3 near layer and (semiconductor or chip or die or IC or active near components) and (inorganic near filler and thermosetting near resin) and (via or opening or open)	USPAT	2002/11/29 21:48
20	BRS	0	"built in module" and (semiconductor or chip or die or IC or active near components) and (inorganic near filler with thermosetting near resin) and (via or opening or open)	USPAT	2002/11/29 21:49
21	BRS	0	"built in module" and (semiconductor or chip or die or IC or active near components) and (inorganic near filler same thermosetting near resin) and (via or opening or open)	USPAT	2002/11/29 21:50
22	BRS	2	"built-in module" and (semiconductor or chip or die or IC or active near components) and (inorganic near filler same thermosetting near resin) and (via or opening or open)	USPAT	2002/11/29 22:06

	Type	Hits	Search Text	DBs	Time Stamp
23	BRS	1	"4299873".PN.	USPAT	2002/11/29 22:00
24	BRS	1	"4417297".PN.	USPAT	2002/11/29 22:00
25	BRS	1	"4800459".PN.	USPAT	2002/11/29 22:01
26	BRS	1	"5045381".PN.	USPAT	2002/11/29 22:01
27	BRS	1	"5153987".PN.	USPAT	2002/11/29 22:01
28	BRS	1	"5324687".PN.	USPAT	2002/11/29 22:02
29	BRS	1	"5401688".PN.	USPAT	2002/11/29 22:02
30	BRS	1	"5401913".PN.	USPAT	2002/11/29 22:02
31	BRS	1	"5412538".PN.	USPAT	2002/11/29 22:03
32	BRS	1	"5481795".PN.	USPAT	2002/11/29 22:03
33	BRS	1	"5484647".PN.	USPAT	2002/11/29 22:03
34	BRS	1	"5651179".PN.	USPAT	2002/11/29 22:03
35	BRS	1	"5481795".PN.	USPAT	2002/11/29 22:03
36	BRS	1	"5484647".PN.	USPAT	2002/11/29 22:03
37	BRS	1	"5651179".PN.	USPAT	2002/11/29 22:04
38	BRS	1	"5652042".PN.	USPAT	2002/11/29 22:04
39	BRS	1	"5677045".PN.	USPAT	2002/11/29 22:04
40	BRS	1	"5806177".PN.	USPAT	2002/11/29 22:04
41	BRS	1	"5806177".PN.	USPAT	2002/11/29 22:05
42	BRS	1	"5888627".PN.	USPAT	2002/11/29 22:05
43	BRS	1	"5939782".PN.	USPAT	2002/11/29 22:05
44	BRS	2	"built-in module" and (semiconductor or chip or die or IC or active near components) and (inorganic near filler and thermosetting near resin) and (via or opening or open)	USPAT	2002/11/29 22:07

	Type	Hits	Search Text	DBs	Time Stamp
45	BRS	118	(semiconductor or chip or die or IC or active near components) and (inorganic near filler same thermosetting near resin) and (via or opening or open)	USPAT	2002/12/01 19:23
46	BRS	4	epoxy near resin with "10 GPa"	USPAT	2002/12/01 18:04
47	BRS	0	epoxy near resin with inorganic near filler with "10 GPa"	USPAT	2002/12/01 17:57
48	BRS	0	epoxy near resin with inorganic near filler with "9 GPa"	USPAT	2002/12/01 17:57
49	BRS	0	epoxy near resin with inorganic near filler with "8 GPa"	USPAT	2002/12/01 17:58
50	BRS	0	epoxy near resin with inorganic near filler with "7 GPa"	USPAT	2002/12/01 17:58
51	BRS	0	epoxy near resin with inorganic near filler with "6 GPa"	USPAT	2002/12/01 17:58
52	BRS	0	epoxy near resin with inorganic near filler with "5 GPa"	USPAT	2002/12/01 17:58
53	BRS	0	epoxy near resin with inorganic near filler with "4 GPa"	USPAT	2002/12/01 17:58
54	BRS	0	epoxy near resin with inorganic near filler with "3 GPa"	USPAT	2002/12/01 17:59
55	BRS	0	epoxy near resin with inorganic near filler with "2 GPa"	USPAT	2002/12/01 17:59
56	BRS	0	epoxy near resin with inorganic near filler with "1 GPa"	USPAT	2002/12/01 17:59
57	BRS	0	epoxy near resin same inorganic near filler with "1 GPa"	USPAT	2002/12/01 18:00
58	BRS	2	epoxy near resin same inorganic near filler with "2 GPa"	USPAT	2002/12/01 18:00
59	BRS	0	epoxy near resin same inorganic near filler with "3 GPa"	USPAT	2002/12/01 18:00

	Type	Hits	Search Text	DBs	Time Stamp
60	BRS	0	epoxy near resin same inorganic near filler with "4 GPa"	USPAT	2002/12/01 18:00
61	BRS	0	epoxy near resin same inorganic near filler with "5 GPa"	USPAT	2002/12/01 18:00
62	BRS	0	epoxy near resin same inorganic near filler with "6 GPa"	USPAT	2002/12/01 18:00
63	BRS	0	epoxy near resin same inorganic near filler with "7 GPa"	USPAT	2002/12/01 18:00
64	BRS	0	epoxy near resin same inorganic near filler with "8 GPa"	USPAT	2002/12/01 18:00
65	BRS	0	epoxy near resin same inorganic near filler with "9 GPa"	USPAT	2002/12/01 18:00
66	BRS	0	epoxy near resin same inorganic near filler with "10 GPa"	USPAT	2002/12/01 18:02
67	BRS	0	epoxy near resin with filler with "10 GPa"	USPAT	2002/12/01 18:02
68	BRS	0	epoxy near resin with filler with "9 GPa"	USPAT	2002/12/01 18:02
69	BRS	0	epoxy near resin with filler with "8 GPa"	USPAT	2002/12/01 18:02
70	BRS	0	epoxy near resin with filler with "7 GPa"	USPAT	2002/12/01 18:02
71	BRS	0	epoxy near resin with filler with "6 GPa"	USPAT	2002/12/01 18:02
72	BRS	0	epoxy near resin with filler with "5 GPa"	USPAT	2002/12/01 18:02
73	BRS	0	epoxy near resin with filler with "4 GPa"	USPAT	2002/12/01 18:03
74	BRS	0	epoxy near resin with filler with "3 GPa"	USPAT	2002/12/01 18:03
75	BRS	0	epoxy near resin with filler with "2 GPa"	USPAT	2002/12/01 18:03
76	BRS	0	epoxy near resin with filler with "1 GPa"	USPAT	2002/12/01 18:03
77	BRS	0	6038113.pn. and resin	USPAT	2002/12/01 18:06
78	BRS	1	6038133.pn. and resin	USPAT	2002/12/01 18:47
79	BRS	6678	"glass transition temperature" and epoxy near resin	USPAT	2002/12/01 18:48

	Type	Hits	Search Text	DBs	Time Stamp
80	BRS	643	"glass transition temperature" with epoxy near resin	USPAT	2002/12/01 19:07
81	BRS	0	"film-shaped passive component" with between with wiring	USPAT	2002/12/01 19:09
82	BRS	0	"film-shaped passive component" with wiring	USPAT	2002/12/01 19:10
83	BRS	0	"film-shaped passive component"	USPAT	2002/12/01 19:10
84	BRS	0	"film-shaped" with ("passive component" or capacitor or resistor) with wiring	USPAT	2002/12/01 19:11
85	BRS	269	("film-shaped" or thin) with ("passive component" or capacitor or resistor) with wiring	USPAT	2002/12/01 19:12
86	BRS	56	("film-shaped" or thin) with ("passive component" or capacitor or resistor) with between with wiring	USPAT	2002/12/01 19:12
87	BRS	40	(semiconductor or chip or die or IC or active near components) and (inorganic near filler same thermosetting near resin) and (via or opening or open)	US-PGPUB ; EPO; JPO; DERWENT; IBM_TDB	2002/12/01 19:33
88	BRS	13	(257/724 or 257/687 or 257/690 or 257/788 or 257/795) and (semiconductor or chip or die or IC or active near components) and (inorganic near filler same thermosetting near resin) and (via or opening or open)	USPAT; US-PGPUB ; EPO; JPO; DERWENT; IBM_TDB	2002/12/01 19:47

	Type	Hits	Search Text	DBs	Time Stamp
89	BRS	12	(361/760 or 361/782 or 310/340 or 310/313 or 264/272.11) and (semiconductor or chip or die or IC or active near components) and (inorganic near filler same thermosetting near resin) and (via or opening or open)	USPAT; US-PGPUB ; EPO; JPO; DERWENT; IBM_TDB	2002/12/ 01 19:39
90	BRS	18	(156/233 or 428/209) and (semiconductor or chip or die or IC or active near components) and (inorganic near filler same thermosetting near resin) and (via or opening or open)	USPAT; US-PGPUB ; EPO; JPO; DERWENT; IBM_TDB	2002/12/ 01 19:49
91	BRS	6	6359235.pn. or 06069259.pn. or 5834850.pn.	USPAT; US-PGPUB ; EPO; JPO; DERWENT; IBM_TDB	2002/12/ 01 19:49
92	BRS	3	6359235.pn. or 06069259.pn. or 5834850.pn.	USPAT; JPO	2002/12/ 01 20:12
93	BRS	3	5172304.pn. or 6038133.pn. or 6060150.pn.	USPAT; JPO	2002/12/ 01 20:12